

REMARKS

Reconsideration and allowance of this application, as amended, is respectfully requested.

This Amendment is in response to the Office Action dated March 9, 2009.

By the present amendment, the claims have been amended to clarify the invention, as will be discussed below.

In particular, the original rejected claims 1-3 have been canceled and replaced with new independent claim 44 and dependent claims 45-52, noting that new independent claim 44 is an amended version of previously pending claim 3. Non-elected claims 4-43 have been canceled without prejudice.

Reconsideration and allowance of independent claim 44 and its dependent claims 45-52 over the 35 USC §102(b) rejection based on Kenji (JP Pub. 04039959) is respectfully requested. By the present amendment, new independent claims 44 and its dependent claims have been presented to clarify distinctions of the present invention over Kenji. In particular, new independent claim 44 specifically includes the features that the back surface of a semiconductor chip is electrically connected with a controlling circuit and:

“the semiconductor chip is adhered over the main surface of the first supporting body via a first adhesive material comprised of a non-conductive adhesive material such that the back surface of the semiconductor chip faces to the main surface of the first supporting body.”

As a result, these features, combined with the other recitations of the overall structure of claim 44, including the specific arrangement of the capacitative element, permits manufacturing a very small size device because the semiconductor chip and the capacitative element are mounted on the main and back surfaces of the first supporting body, respectively.

More specifically, in the arrangement defined by independent claim 44, as noted above, the back surface of the semiconductor chip is electrically connected with the controlling circuit of the semiconductor chip. However, it is also possible to electrically connect the first electrode of the capacitive element with the back surface of the first supporting body via a conductive material because the semiconductor chip is adhered to the main surface of the first supporting body via a non-conductive material. This permits maintaining reliability of the semiconductor device, while still providing for miniaturization.

Turning to the Kenji reference, although this is of general interest, it is respectfully submitted that it clearly neither teaches the above-noted claimed features of the back surface of the semiconductor chip being electrically connected with the controlling circuit and adhering the semiconductor chip to the main surface of the first supporting body via a first adhesive film comprised of a non-conductive adhesive material such that the back surface of the semiconductor chip faces to the main surface of the first supporting body. Instead, the back surface of the semiconductor chip of Kenji is directly attached to the main surface of the supporting body with a conductive relationship. This is clear from the statement in the Abstract of Kenji which states:

"A semiconductor chip 1 fixed on a stage 3 is electrically connected to predetermined lead terminals with metal filament (Au wire) 4 by wire bending or the like."

As such, there is no teaching or suggestion in Kenji for the feature of claim 44 of adhering a semiconductor chip to the main surface of the first supporting body via a non-conductive material while electrically connecting the back surface of the semiconductor chip with a controlling circuit. Therefore, reconsideration and allowance of newly presented independent claim 44 is respectfully requested.

Reconsideration and allowance of the dependent claims 45-52 is also respectfully requested. These claims define further specific features of the present invention concerning the resin sealing body, the construction of the leads to include first and second leads, and the relative arrangement of respective claimed elements which, when considered with the particular above-noted features of independent claim 44, serve to define even further combinations not at all suggested by the cited reference to Kenji. Therefore, reconsideration and allowance of these dependent claims is also respectfully requested.

If the Examiner believes that there are any other points which may be clarified or otherwise disposed of either by telephone discussion or by personal interview, the Examiner is invited to contact Applicants' undersigned attorney at the number indicated below.

To the extent necessary, Applicants petition for an extension of time under 37 CFR 1.136. Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to the Antonelli, Terry, Stout & Kraus, LLP Deposit Account No. 01-2135 (Docket No. 1374.45607X00), and please credit any excess fees to such deposit account.

Respectfully submitted,
ANTONELLI, TERRY, STOUT & KRAUS, LLP

By /Gregory E. Montone
Gregory E. Montone
Registration No. 28,141

GEM/dks
1300 North Seventeenth Street, Suite 1800
Arlington, Virginia 22209
Telephone: (703) 312-6600
Facsimile: (703) 312-6666